

Global Semiconductor Assembly and Packaging Equipment Market Growth (Status and Outlook) 2025-2031

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Abstracts

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The global Semiconductor Assembly and Packaging Equipment market size is predicted to grow from US\$ 4853 million in 2025 to US\$ 7220 million in 2031; it is expected to grow at a CAGR of 6.8% from 2025 to 2031.

Semiconductor Assembly and Packaging Equipment is used for an integrated chip to function, it needs to be connected to the package or directly to the printed circuit. This involves wire bonding, die-bonding, and dicing. Also, it is a back end process of chip formation. Semiconductor chip assembly is also a key component of the semiconductor supply chain.

The global semiconductor assembly and packaging equipment market refers to the market for tools and machinery used in the assembly and packaging processes of semiconductor devices. Semiconductor assembly and packaging equipment are essential in the manufacturing and production of integrated circuits, chips, and other semiconductor components.

Semiconductor assembly and packaging equipment play a crucial role in the final stage of semiconductor device manufacturing. These equipment are responsible for assembling and packaging individual silicon chips into functional units, which are then integrated into electronic devices. The assembly and packaging processes ensure the protection, electrical connection, and reliability of the semiconductor devices.

The market for semiconductor assembly and packaging equipment is driven by several

factors, including the increasing demand for smaller and more powerful electronic devices, advancements in semiconductor packaging technology, and the growing need for cost-effective manufacturing solutions. As consumer electronics, automotive, and communication sectors continue to evolve, the demand for advanced packaging technologies and equipment is expected to rise.

The market can be segmented based on the type of equipment, such as die bonders, wire bonders, molding machines, testing equipment, and others. Die bonders and wire bonders are used for attaching the semiconductor chips to the package, while molding machines are used to encapsulate the chips with protective materials. Testing equipment ensures the quality and reliability of the assembled semiconductor devices.

Geographically, Asia-Pacific holds a significant share in the semiconductor assembly and packaging equipment market, primarily driven by the presence of major semiconductor manufacturing hubs in countries like China, Taiwan, South Korea, and Japan. The region is known for high-volume semiconductor production and rapid technological advancements. North America and Europe also contribute to the market due to the presence of established semiconductor companies and semiconductor packaging facilities.

Key players in the global semiconductor assembly and packaging equipment market include industry leaders such as ASM Pacific Technology, Kulicke & Soffa Industries, Tokyo Electron Limited, Applied Materials, and Advantest Corporation. These companies are engaged in the research, development, and manufacturing of advanced equipment to meet the ever-increasing demands of the semiconductor industry.

The market for semiconductor assembly and packaging equipment is expected to witness steady growth in the coming years, driven by factors such as the increasing demand for compact electronic devices, the adoption of advanced packaging technologies like System-in-Package (SiP) and Fan-out Wafer-Level Packaging (FOWLP), and the emergence of new applications such as Internet of Things (IoT) and artificial intelligence (AI). However, factors like high initial costs, the complexity of equipment integration, and the need for skilled workforce may pose challenges to market growth.

LPI (LP Information)' newest research report, the "Semiconductor Assembly and Packaging Equipment Industry Forecast" looks at past sales and reviews total world Semiconductor Assembly and Packaging Equipment sales in 2024, providing a comprehensive analysis by region and market sector of projected Semiconductor

Assembly and Packaging Equipment sales for 2025 through 2031. With Semiconductor Assembly and Packaging Equipment sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Semiconductor Assembly and Packaging Equipment industry.

This Insight Report provides a comprehensive analysis of the global Semiconductor Assembly and Packaging Equipment landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyses the strategies of leading global companies with a focus on Semiconductor Assembly and Packaging Equipment portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Semiconductor Assembly and Packaging Equipment market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Semiconductor Assembly and Packaging Equipment and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Semiconductor Assembly and Packaging Equipment.

This report presents a comprehensive overview, market shares, and growth opportunities of Semiconductor Assembly and Packaging Equipment market by product type, application, key players and key regions and countries.

Segmentation by Type:

Electroplating Equipment

Inspection and Cutting Equipment

Lead Bonding Equipment

Chip Bonding Equipment

Others

Segmentation by Application:

Automotive

Enterprise Storage

Consumer Electronics

Healthcare Devices

Others

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analyzing the company's coverage, product portfolio, its market penetration.

Advantest

Accrutech

Shinkawa

KLA-Tencor

Teradyne Inc.

Amkor Technology

Tokyo Electron Limited

Lam Research Corporation

ASML Holding N.V

Applied Materials

Toray Engineering

Kulicke & Soffa Industries

Hesse Mechatronics

Palomar Technologies

West Bond

DIAS Automation

Screen Holdings Co. Ltd

Hitachi High-Technologies Corporation

HYBONDASM Pacific Technology

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